



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Wen-Chun ZHENG *et al.*  
Serial No.: 10/085,183  
Filed : February 27, 2002  
Title : SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO HEAT  
REMOVAL DEVICE AND METHOD OF MANUFACTURING SAME

Art Unit : 2815  
Examiner : Chris Chu  
Confirmation No.: 1430

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**REPLY UNDER 37 CFR § 1.111**

In response to the Office Action dated November 28, 2003, please amend the present application as follows and consider the included remarks.

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